

**AMENDMENTS TO THE DRAWINGS**

The two attached sheets of drawings include changes to FIGs. 1 and 2 and replace the original sheets including FIGs. 1 and 2, respectively. In Figure 1, previously omitted legend (PRIOR ART) has been added. In Figure 2, numeral designation of the folder has been amended from 150 to 250.

**REMARKS**

Claims 1-8 are pending with Claims 1, 6 and 8 being independent claims.

Figure 1 was objected to due to lack of a legend such as "Prior Art."

Claims 1-8 were rejected on the ground of nonstatutory obviousness-type double patenting as being unpatentable over claims 1-8 of Ryu (U.S. Pat. No. 6,808,402), whose assignee is Samsung Electronics Co., Ltd.

Claims 1-8 were further rejected under 35 U.S.C. § 103(a) as being unpatentable in view of Braxton (U.S. Pat. No. 6,134,121).

Regarding the objection of Figure 1, a replacement sheet of drawing for Figure 1 is attached hereto and is believed to overcome the objection.

Regarding the rejection of Claims 1-8 on the ground of nonstatutory obviousness-type double patenting, the Examiner stated the claims are not patentably distinct from the claims in Ryu. Both Ryu and the present application offer solutions in Electro Magnetic Compliance (EMC).

Claim 1 of the present application recites "a hinge device comprising . . . a conductive hinge housing . . . a conductive coil spring . . . a conductive contact pin . . . and a conductive hinge dummy." Referring to Figs. 4 and 5, the ground path between the folder 250 and the main body 210 runs through the ground of the folder 250, the electrically conductive hinge housing 310, the full helical length of the electrically conductive coil spring 340, the electrically conductive contact pin 350, the electrically conductive hinge dummy 360, and the ground of the main body 210.

Meanwhile, in Ryu, referring to FIGs. 2 and 5 and col. 5 lines 53-62, the ground path runs through the ground of the folder 150, the first contact piece 160, the hinge housing 210, the hinge stopper 250, the hinge dummy 130, the second contact piece 140, and the ground of the main body 110. It is respectfully noted that the coil spring 240 is excluded from the electrical path. It is well known in the EMC art that when there is a change in the ground path or in composition of the electrically conductive elements on the ground path, EMC performance will change.

Similar rationale applies to independent Claims 6 and 8 of the present application.

Clearly, the present application patentably differs from Ryu in view of structure and EMC performance.

Regarding the rejection of Claims 1-8 under 35 U.S.C. § 103(a), the Examiner stated that Braxton renders the claims obvious.

The present application offers an EMC solution to mobile communication terminal having a main body and a folder. The folder is movable with respect to the main body. The inventive solution of the present application includes a hinge device that is electrically conductive, to address a need to electrically connect the ground of the main body and the ground to the folder to enhance EMC performance.

Meanwhile, Braxton offers an EMC solution that focuses merely on applying a conductive heat shrinkable composite laminate wrapper on a sole circuit pack. Braxton fails to disclose or suggest an electrically conductive hinge device that can electrically connect the grounds of two moveable circuit packs per the present application. Further, the laminate wrapper of Braxton may give rise to a cooling problem of the circuit pack.

Clearly, the claims of the present application patentably differ from Braxton in view of structure and problem solutions.

In view of the preceding amendments and remarks, it is respectfully submitted that all pending claims herein, namely Claims 1-8, are in condition for allowance. Should the Examiner believe that a telephone conference or personal interview would facilitate resolution of any remaining matters, the Examiner may contact Applicant's attorney at the number given below.

Respectfully submitted,



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